

CLAIMS

1. A shock-resistant system for operatively interconnecting modules within a computer system to enable data to be transmitted and received therebetween comprising:

a. a first module having at least one tri-stateable digital transmitter element formed thereon for transmitting data from said first module, said first module having at least one digital receiver element formed thereon for receiving data for said first module, said data transmitted and received by said first module substantially conforming to a standardized infrared communications scheme protocol;

b. a second module having at least one tri-stateable digital transmitter element formed thereon for transmitting data from said second module, said second module having at least one digital receiver element formed thereon for receiving data for said second module, said data transmitted and received by said second module substantially conforming to said standardized infrared communications scheme protocol utilized by said first module; and

c. wherein said at least one transmitting element of said first module is electrically interfaced with said at least one receiver element of said second module and said at least one transmitting element of said second module is electrically interfaced to said at least one receiver element of said first module such that said at least one transmitter element on said first module is operative to transmit a signal to said at least one receiving element on said second module and said at least one transmitter element of said second module is operative to transmit a digital signal to said at least one receiver element of said first module.

2. The system of Claim 1 wherein said infrared communications scheme protocol comprises a protocol developed by the Infrared Data Association.

3. The system of Claim 1 wherein said first and second modules are housed within an enclosure.

4. The system of Claim 1 wherein said first and second modules are operative to run an embedded application.

5. The system of Claim 1 wherein said system comprises a multiplicity of modules wherein each respective one of said 10 multiplicity of modules has at least one dedicated transmitter element and receiver element formed thereon, each respective one of said multiplicity of modules being electrically interfaced to one another via said transmitter and receiver elements formed thereon such that said modules 15 are operative to transmit and receive data therebetween.

6. A method for operatively interconnecting modules within a computer to enable data to be transmitted and received therebetween comprising:

20 a. providing a first module having at least one transmitter element and at least one receiver element formed thereon, said data transmitted and received by said first module substantially conforming to a standardized infrared communications scheme protocol;

25 b. providing a second module having at least one transmitter element and at least one receiver element formed thereon, said data transmitted and received by said second module substantially conforming to a standardized infrared communications scheme or protocol;

30 c. electrically interfacing said first module with said second module such that at least one transmitting element of said first module is electrically interfaced with said at least one receiving element of said second module and said at least one transmitting element of said second module is electrically

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interfaced to said at least one receiving element of
said first module such that said at least one
transmitter element on said first module is operative
to transmit a signal to said receiver on said first
module and said at least one transmitter element of
said second module is operative to transmit a signal
to said at least one receiver of said first module.

5 7. The method of Claim 8 wherein in steps a) and b), said
 infrared communications scheme protocol comprises a
 protocol developed by the Infrared Data Association.

10 8. The method of Claim 8 wherein in steps a) and b), said
 first and second modules are housed within an enclosure.

15 9. The method of Claim 8 wherein in step c), said first
 and second circuit cards are operatively coupled to run an
 embedded application.

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